

FDU6N25

N-Channel UniFET™ MOSFET

250 V, 4.4 A, 1.1 Ω

Features

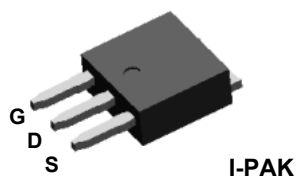
- $R_{DS(on)} = 1.1 \Omega$ (Max.) @ $V_{GS} = 10 V$, $I_D = 2.2 A$
- Low Gate Charge (Typ. 4.5 nC)
- Low C_{rss} (Typ. 5 pF)
- 100% Avalanche Tested

Applications

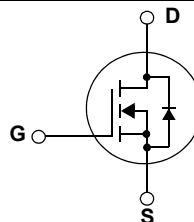
- LCD/LED/PDP TV
- Consumer Appliances
- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply

Description

UniFET™ MOSFET is Fairchild Semiconductor®'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.



I-PAK



Absolute Maximum Ratings

| Symbol | Parameter | | FDU6N25 | Unit |
|----------------|--|--------------------------------------|-------------|---------------|
| V_{DSS} | Drain-Source Voltage | | 250 | V |
| I_D | Drain Current | - Continuous ($T_C = 25^\circ C$) | 4.4 | A |
| | | - Continuous ($T_C = 100^\circ C$) | 2.6 | A |
| I_{DM} | Drain Current | - Pulsed (Note 1) | 18 | A |
| V_{GSS} | Gate-Source voltage | | ± 30 | V |
| E_{AS} | Single Pulsed Avalanche Energy (Note 2) | | 12 | mJ |
| I_{AR} | Avalanche Current (Note 1) | | 4.4 | A |
| E_{AR} | Repetitive Avalanche Energy (Note 1) | | 5 | mJ |
| dv/dt | Peak Diode Recovery dv/dt (Note 3) | | 4.5 | V/ns |
| P_D | Power Dissipation | ($T_C = 25^\circ C$) | 50 | W |
| | | - Derate above $25^\circ C$ | 0.4 | W/ $^\circ C$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | | -55 to +150 | $^\circ C$ |
| T_L | Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds | | 300 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | FDU6N25 | Unit |
|-----------------|---|---------|--------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case, Max. | 2.5 | $^\circ C/W$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient, Max. | 110 | |

Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|---------|---------|-----------|------------|----------|
| FDU6N25 | FDU6N25 | I-PAK | - | - | 70 |

Electrical Characteristics T_C = 25°C unless otherwise noted

| Symbol | Parameter | Conditions | Min. | Typ. | Max | Unit |
|--|---|--|----------|----------|---------|----------|
| Off Characteristics | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} = 0V, I _D = 250μA | 250 | -- | -- | V |
| ΔBV _{DSS} / ΔT _J | Breakdown Voltage Temperature Coefficient | I _D = 250μA, Referenced to 25°C | -- | 0.25 | -- | V/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 250V, V _{GS} = 0V V _{DS} = 200V, T _C = 125°C | -- -- | -- -- | 1 10 | μA μA |
| I _{GSSF} | Gate-Body Leakage Current, Forward | V _{GS} = 30V, V _{DS} = 0V | -- | -- | 100 | nA |
| I _{GSSR} | Gate-Body Leakage Current, Reverse | V _{GS} = -30V, V _{DS} = 0V | -- | -- | -100 | nA |
| On Characteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} , I _D = 250μA | 3.0 | -- | 5.0 | V |
| R _{DS(on)} | Static Drain-Source On-Resistance | V _{GS} = 10V, I _D = 2.2A | -- | 0.9 | 1.1 | Ω |
| g _{FS} | Forward Transconductance | V _{DS} = 40V, I _D = 2.2A | -- | 5.5 | -- | S |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz | -- | 194 | 250 | pF |
| C _{oss} | Output Capacitance | | -- | 38 | 50 | pF |
| C _{rss} | Reverse Transfer Capacitance | | -- | 5 | 8 | pF |
| Switching Characteristics | | | | | | |
| t _{d(on)} | Turn-On Delay Time | V _{DD} = 125V, I _D = 6A R _G = 25Ω (Note 4) | -- | 10 | 30 | ns |
| t _r | Turn-On Rise Time | | -- | 25 | 60 | ns |
| t _{d(off)} | Turn-Off Delay Time | | -- | 7 | 24 | ns |
| t _f | Turn-Off Fall Time | | -- | 12 | 34 | ns |
| Q _g | Total Gate Charge | V _{DS} = 200V, I _D = 6A V _{GS} = 10V (Note 4) | -- | 4.5 | 6 | nC |
| Q _{gs} | Gate-Source Charge | | -- | 1.5 | -- | nC |
| Q _{gd} | Gate-Drain Charge | | -- | 1.8 | -- | nC |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I _S | Maximum Continuous Drain-Source Diode Forward Current | | -- | -- | 4.4 | A |
| I _{SM} | Maximum Pulsed Drain-Source Diode Forward Current | | -- | -- | 18 | A |
| V _{SD} | Drain-Source Diode Forward Voltage | V _{GS} = 0V, I _S = 4.4A | -- | -- | 1.4 | V |
| t _{rr} | Reverse Recovery Time | V _{GS} = 0V, I _S = 6A | -- | 145 | -- | ns |
| Q _{rr} | Reverse Recovery Charge | dI _F /dt =100A/μs | -- | 0.55 | -- | μC |

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L = 1.2mH, I_{AS} = 4.4A, V_{DD} = 50V, R_G = 25Ω, Starting T_J = 25°C
3. I_{SD} ≤ 4.4A, di/dt ≤ 200A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

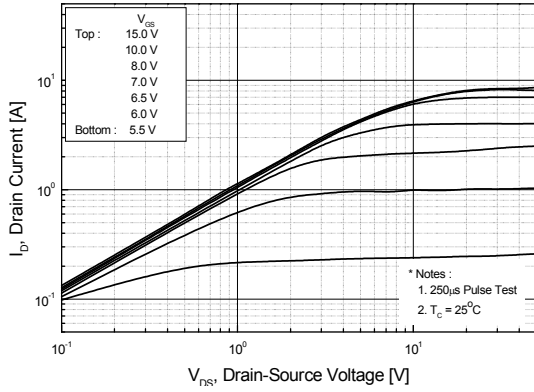


Figure 2. Transfer Characteristics

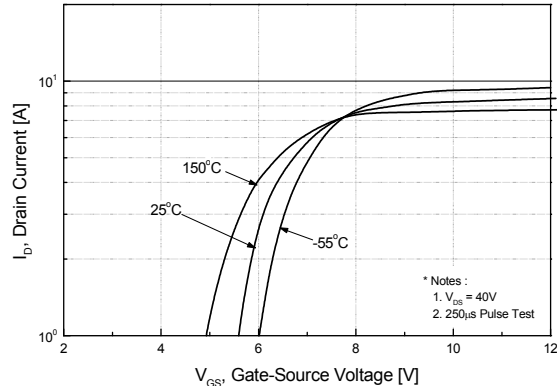


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

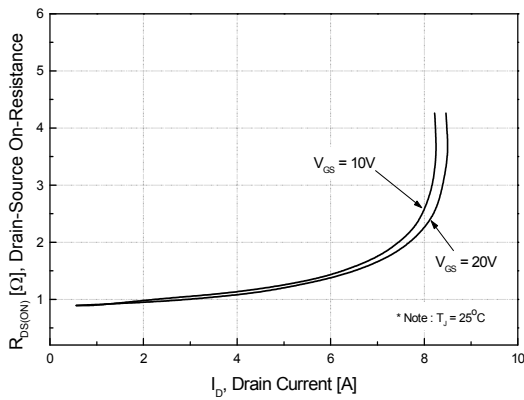


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

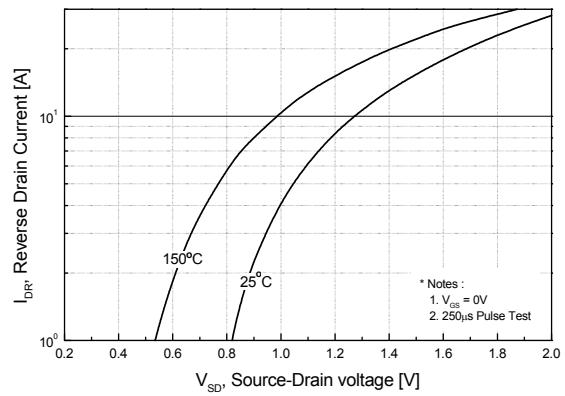


Figure 5. Capacitance Characteristics

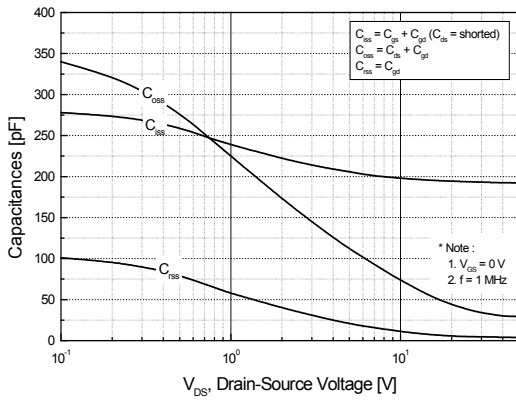
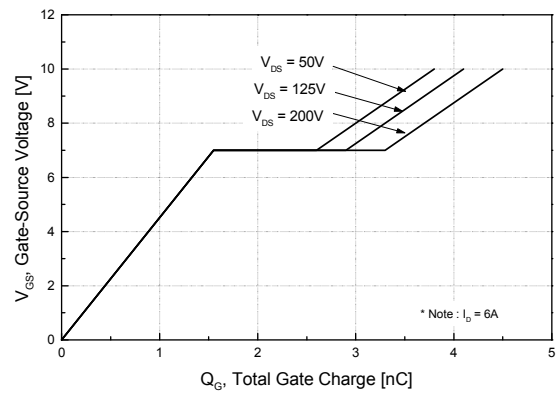


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

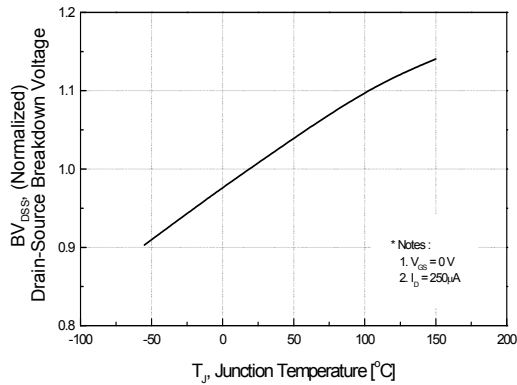


Figure 8. On-Resistance Variation vs. Temperature

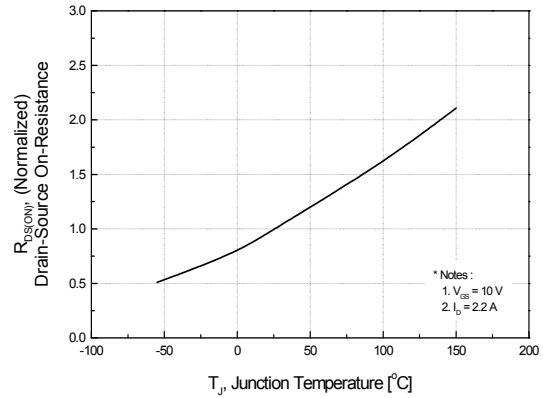


Figure 9. Maximum Safe Operating Area

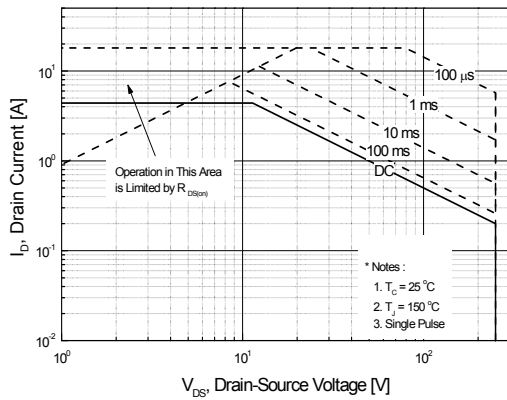


Figure 10. Maximum Drain Current vs. Case Temperature

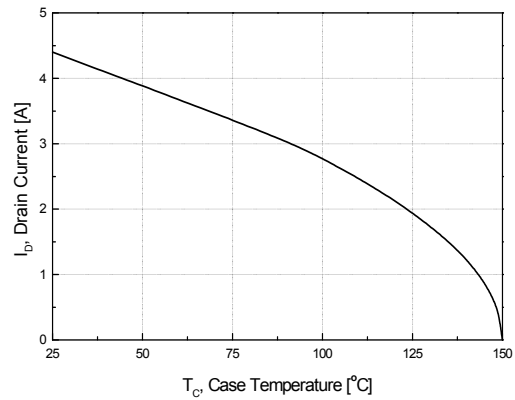
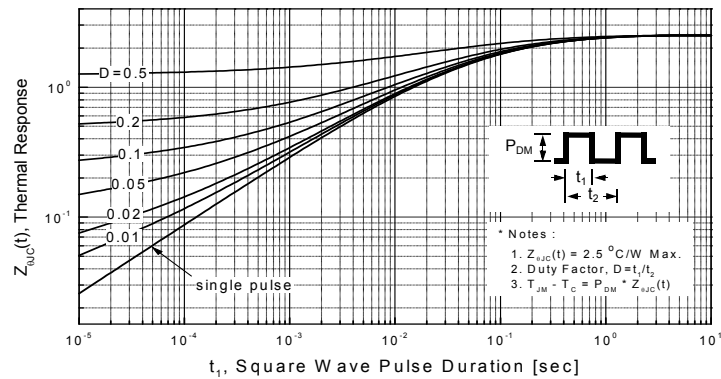
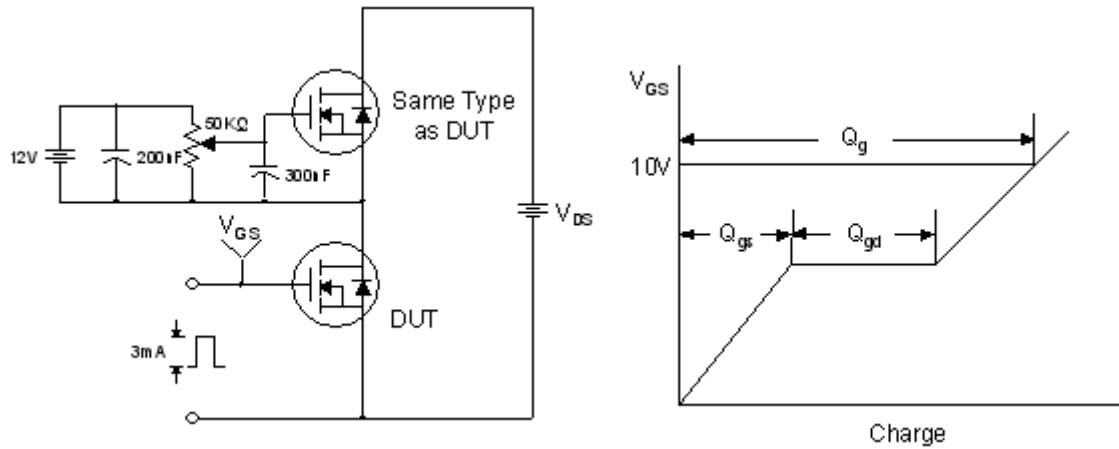


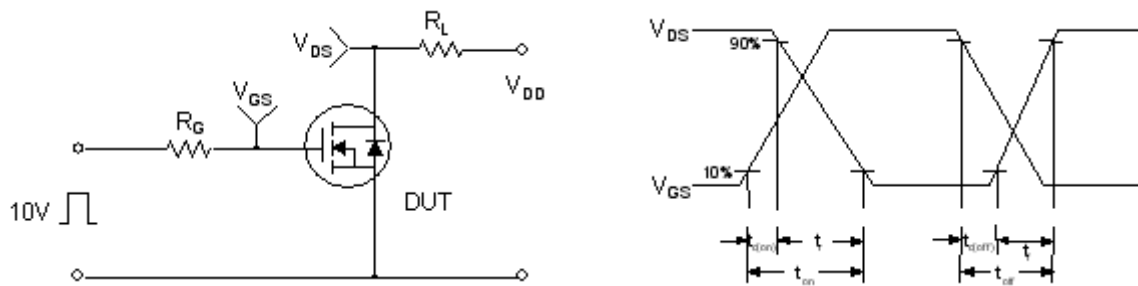
Figure 11. Transient Thermal Response Curve



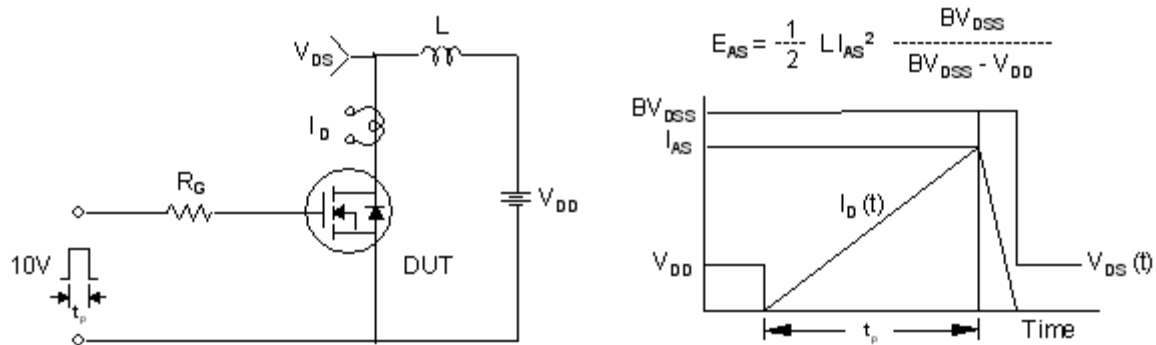
Gate Charge Test Circuit & Waveform



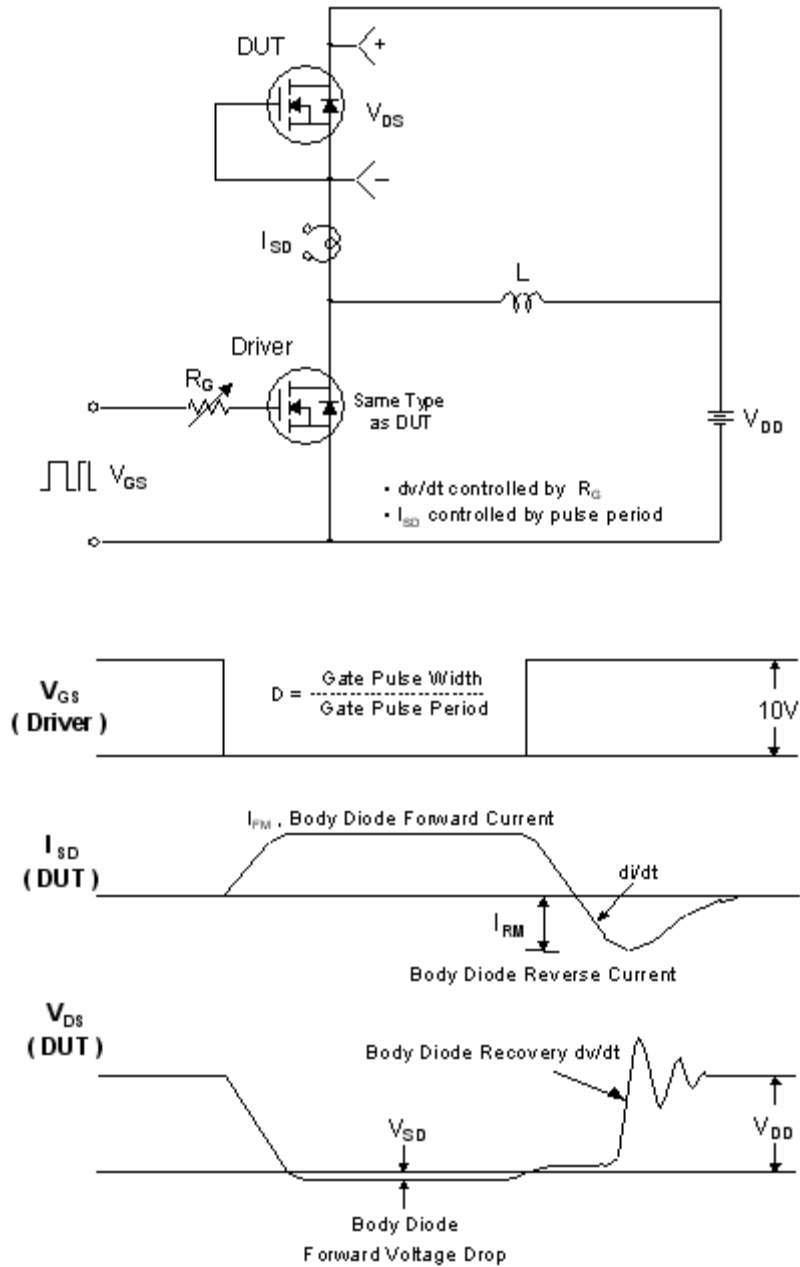
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

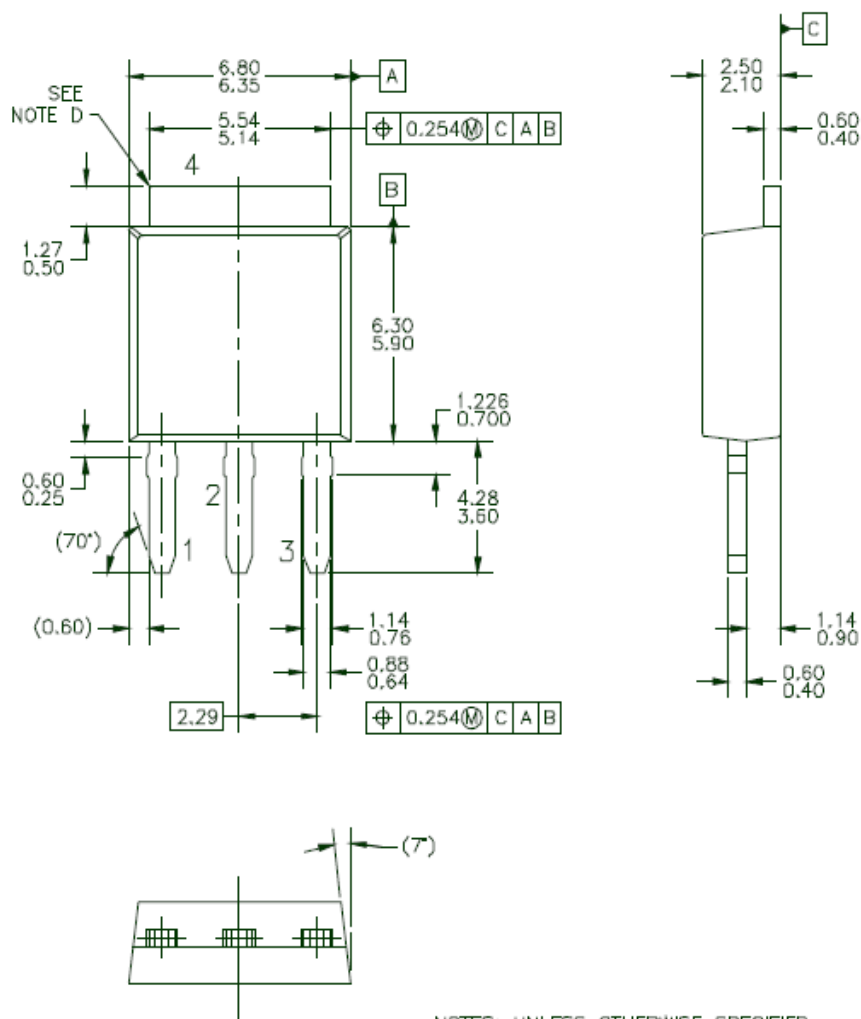


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Mechanical Dimensions

I-PAK (Short Lead)



NOTES: UNLESS OTHERWISE SPECIFIED

- A) ALL DIMENSIONS ARE IN MILLIMETERS.
- B) PACKAGE BODY REFERENCE: JEDEC, TO-251, ISSUE D, VARIATION AA, DATED JUNE 2002.
- C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.
- E) DRAWING FILE NAME: TO251B03_3



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